

April 17, 2018



Re: Issue of Hitachi Capital Corporation's 71st and 72nd Unsecured Straight Bonds  
(with Limited Interbond Pari Passu Clause)

Hitachi Capital Corporation wishes to announce that it has determined the following terms and conditions for the issuance of its 71st, and 72nd unsecured straight bonds.

- Description -

		71st	72nd
1.	Total issue amount	¥ 15 billion	¥ 10 billion
2.	Denomination per bond	¥ 100 million	
3.	Interest rate	0.040% per annum	0.280% per annum
4.	Payment amount	¥100 per ¥100 bond face value	
5.	Redemption price	¥100 per ¥100 bond face value	
6.	Redemption date	The principal of the bond will be redeemed in full on March 19, 2021	The principal of the bond will be redeemed in full on April 18, 2025
7.	Interest payment dates	March 20 and September 20 of each year	April 20 and October 20 of each year
8.	Offering period	April 17, 2018	
9.	Payment date	April 23, 2018	
10.	Offering method	Offering to the general public	
11.	Collateral	No collateral or guarantee is pledged and no assets are specifically reserved to secure these bonds	
12.	Financial covenants	Negative pledge clause (with limited interbond pari passu clause)	
13.	Underwriters	Mitsubishi UFJ Morgan Stanley Securities Co., Ltd. SMBC Nikko Securities Inc. BNP Paribas Securities (Japan) Limited SBI SECURITIES Co.,Ltd.	Mitsubishi UFJ Morgan Stanley Securities Co., Ltd. SMBC Nikko Securities Inc. BNP Paribas Securities (Japan) Limited
14.	Place for handling subscriptions	Head office and domestic branches of underwriters	
15.	Financial agent	MUFG Bank, Ltd.	
16.	Book-entry transfer institution	Japan Securities Depository Center, Incorporated	
17.	Ratings (to be obtained)	A+ (Rating and Investment Information, Inc.) AA- (Japan Credit Rating Agency, Ltd.)	